



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR MINI QFN-16

Stress	Sample Size	Device Hr./Cyc	Condition	Total Fails	Fail Percentage
85/85	165	27,720	85 °C, 85 % RH	0	0.00
BOND INT	200	150,000	200 °C + N2	0	0.00
HAST	165	165,500	130 °C, 85 % RH	0	0.00
Pressure Pot	165	15,840	121°, 15 PSIG	0	0.00
Solder DUNK	55	165	260 °C, 10 SEC	0	0.00
Solderability	45	360	883 M2003	0	0.00
Temp Cycle	220	137,500	- 65 °C - 150 °C	0	0.00